

18. (New) Apparatus as specified in claim 17 wherein said fork is arranged to be move under a placement location for said wafers on said wafer holding device.

19. (New) Apparatus as specified in claim 17 wherein said heating plate and said cooling plate are arranged next to one another in said chamber.

20. (New) Apparatus as specified in claim 19 wherein said heating plate and said cooling plate are arranged one behind the other in said chamber.

21. (New) Apparatus as specified in claim 17 wherein there is provided a cooling device for cooling said internal handling device.

22. (New) Apparatus as specified in any of claims 17 through 21 wherein there are provided multiple heating and cooling plates arranged in a stack in said chamber.

23. (New) Apparatus as specified in claim 22 wherein said internal and external handling devices are arranged to load wafers on said plate sequentially.

24. (New) Apparatus as specified in claim 22 wherein said internal and external handling devices are arranged to load wafers on said plate simultaneously.

25. (New) Apparatus as specified in claim 17 wherein said fork is arranged to be preheated.

26. (New) Apparatus as specified in claim 25 wherein said fork is arranged to contact said heating plate for said preheating.

27. (New) Apparatus as specified in claim 17 wherein there is provided an additional internal handling device.

28. (New) Apparatus as specified in claim 17 wherein there are provided multiple chambers arranged in a stack.

29. (New) Apparatus as specified in claim 17 wherein said chamber has first and second openings and wherein there are provided two of said external handing devices, one for transferring wafers through each of said openings.

30. (New) Apparatus as specified in claim 17 wherein said chamber and said external handling device are surrounded by an enclosure.

31. (New) Apparatus as specified in claim 30 wherein said enclosure is purged by gas at a low overpressure.